AOD600A70-VB Datasheet

N-Channel 700V (D-S) Super Junction Power MOSFET

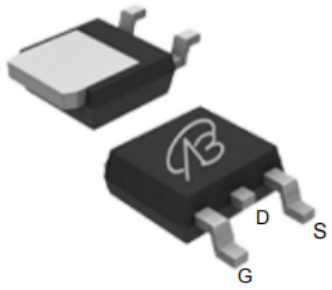
PRODUCT SUMMARY		
V_{DS} (V) at T_J max.	700	
$R_{DS(on)}$ typ. (Ω) at 25 °C	V_{GS} = 10 V	0.560

FEATURES

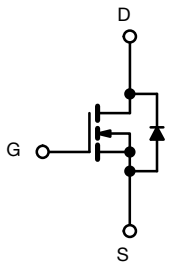
- Low figure-of-merit (FOM) R_{on} x Q_g
- Low input capacitance (C_{iss})
- Reduced switching and conduction losses
- Ultra low gate charge (Q_g)
- Avalanche energy rated (UIS)

RoHS COMPLIANT
HALOGEN FREE

TO-252



Top View



N-Channel MOSFET

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)

ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C, unless otherwise noted)

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V_{DS}	700	V
Gate-source voltage			V_{GS}	± 30	
Continuous drain current (T_J = 150 °C)	V_{GS} at 10 V	T_C = 25 °C	I_D	8	A
		T_C = 100 °C		5	
Pulsed drain current [a]			I_{DM}	24	
Linear derating factor				1.7	W/°C
Single pulse avalanche energy [b]			E_{AS}	330	mJ
Maximum power dissipation			P_D	180	W
Operating junction and storage temperature range			T_J, T_{stg}	-55 to +150	°C
Drain-source voltage slope	T_J = 125 °C		dV/dt	50	V/ns
Reverse diode dV/dt [d]				5.1	
Soldering recommendations (peak temperature) [c]	For 10 s			260	°C

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature
b. V_{DD} = 100 V, starting T_J = 25 °C, L = 30 mH, R_g = 25 Ω, I_{AS} = 4A
c. 1.6 mm from case
d. $I_{SD} \leq I_D$, dI/dt = 100 A/μs, starting T_J = 25 °C

THERMAL RESISTANCE RATINGS				
PARAMETER	**SYMBOL**	**TYP.**	**MAX.**	**UNIT**
Maximum junction-to-ambient	R_{thJA}	-	62	°C/W
Maximum junction-to-case (drain)	R_{thJC}	-	0.85	

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)						
PARAMETER	**SYMBOL**	**TEST CONDITIONS**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Static						
Drain-source breakdown voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 µA	700	-	-	V
V_{DS} temperature coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, I_D = 1 mA	-	1.08	-	V/°C
Gate-source threshold Voltage (N)	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA	2.0	-	4.0	V
Gate-source leakage	I_{GSS}	V_{GS} = ± 20 V	-	-	± 100	nA
		V_{GS} = ± 30 V	-	-	± 1	µA
Zero gate voltage drain current	I_{DSS}	V_{DS} = 700 V, V_{GS} = 0 V	-	-	1	µA
		V_{DS} = 560 V, V_{GS} = 0 V, T_J = 125 °C	-	-	10	
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS} = 10 V, I_D =6A	-	0.560	-	Ω
Forward transconductance	g_{fs}	V_{DS} = 30 V, I_D = 5 A	-	8.7	-	S
Dynamic						
Input capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 100 V, f = 1 MHz	-	2300	-	pF
Output capacitance	C_{oss}		-	51	-	
Reverse transfer capacitance	C_{rss}		-	12	-	
Effective output capacitance, energy related [a]	$C_{o(er)}$	V_{DS} = 0 V to 480 V, V_{GS} = 0 V	-	48	-	
Effective output capacitance, time related [b]	$C_{o(tr)}$		-	205	-	
Total gate charge	Q_g	V_{GS} = 10 V, I_D = 5 A, V_{DS} = 480 V	-	25	-	nC
Gate-source charge	Q_{gs}		-	8	-	
Gate-drain charge	Q_{gd}		-	10	-	
Turn-on delay time	$t_{d(on)}$	V_{DD} = 480 V, I_D = 5 A, V_{GS} = 10 V, R_g = 9.1 Ω	-	12	24	ns
Rise time	t_r		-	14	23	
Turn-off delay time	$t_{d(off)}$		-	61	110	
Fall time	t_f		-	16	-	
Gate input resistance	R_g	f = 1 MHz, open drain	0.3	0.7	1.4	Ω
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	8	A
Pulsed diode forward current	I_{SM}		-	-	24	
Diode forward voltage	V_{SD}	T_J = 25 °C, I_S = 5 A, V_{GS} = 0 V	-	-	1.2	V
Reverse recovery time	t_{rr}	T_J = 25 °C, I_F = I_S = 5 A, dI/dt = 100 A/µs, V_R = 25 V	-	55	110	ns
Reverse recovery charge	Q_{rr}		-	6.4	12.8	µC
Reverse recovery current	I_{RRM}		-	27	-	A

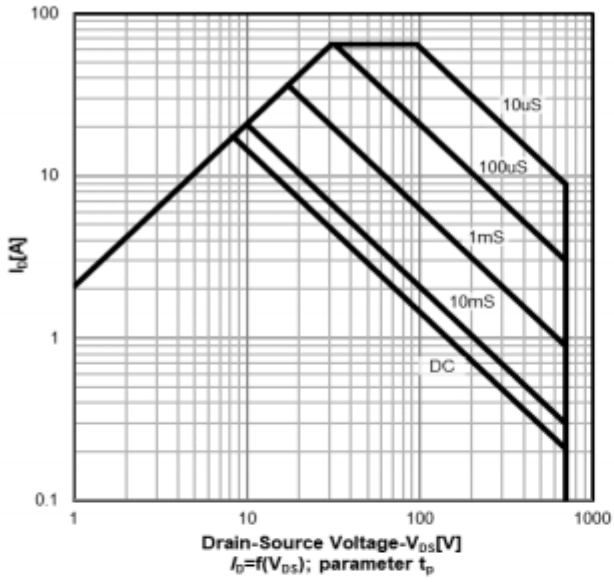
Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

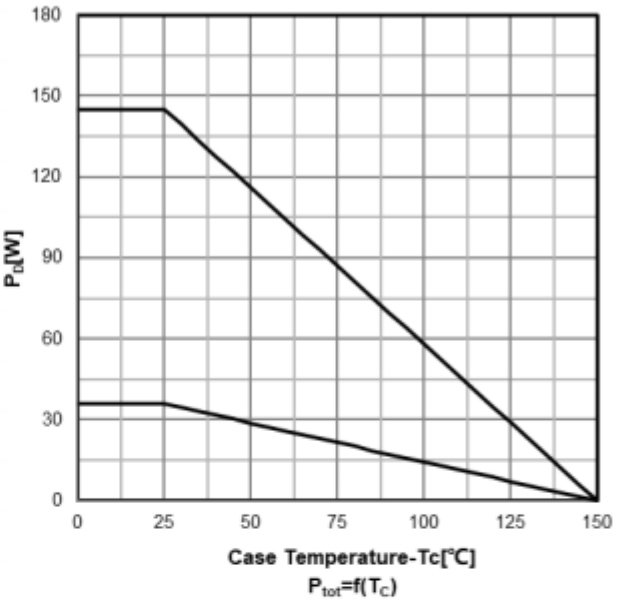
b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

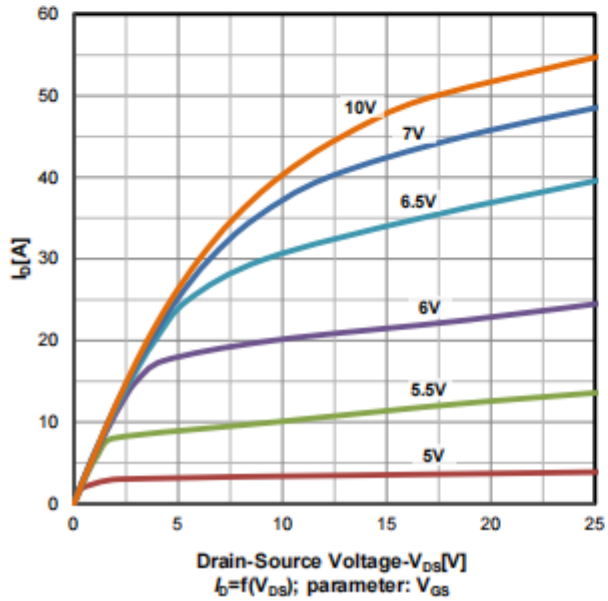
Safe operating area TC=25 ℃
TO-252



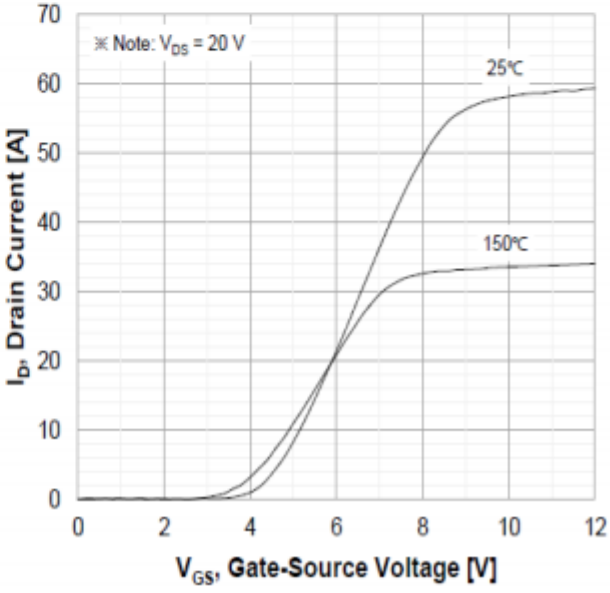
Power dissipation



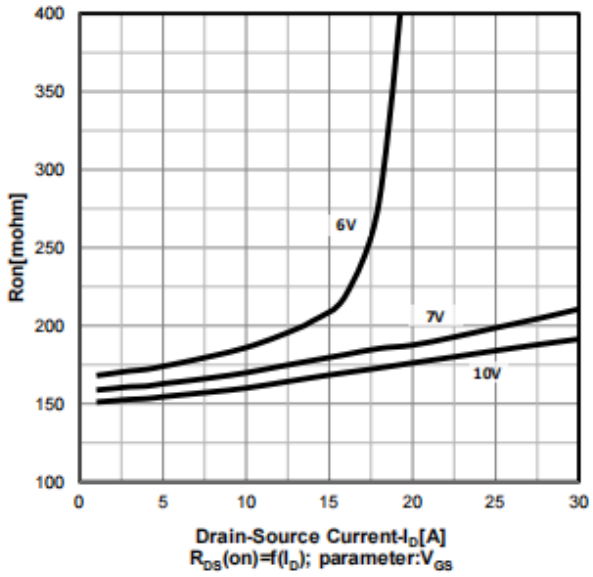
Typ. output characteristics T_j=25 ℃



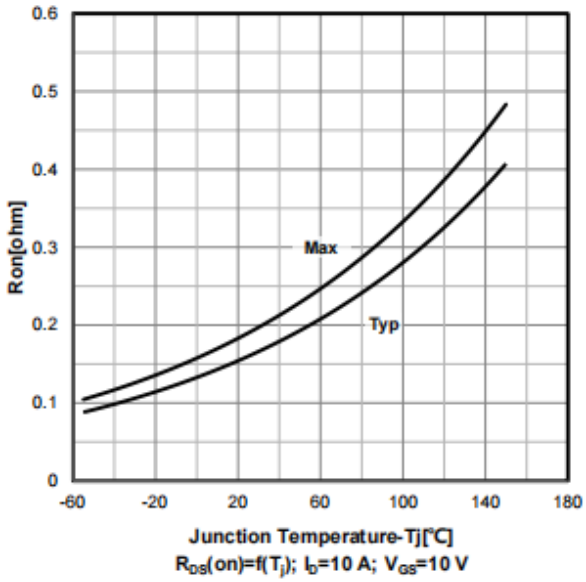
Transfer characteristics



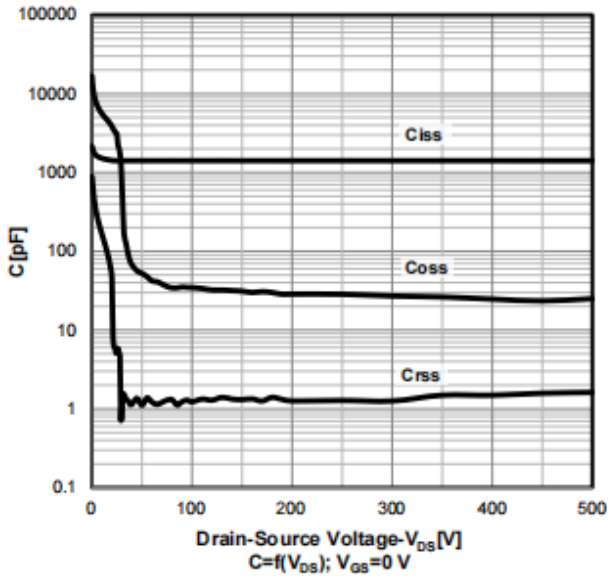
Typ. drain-source on-state resistance



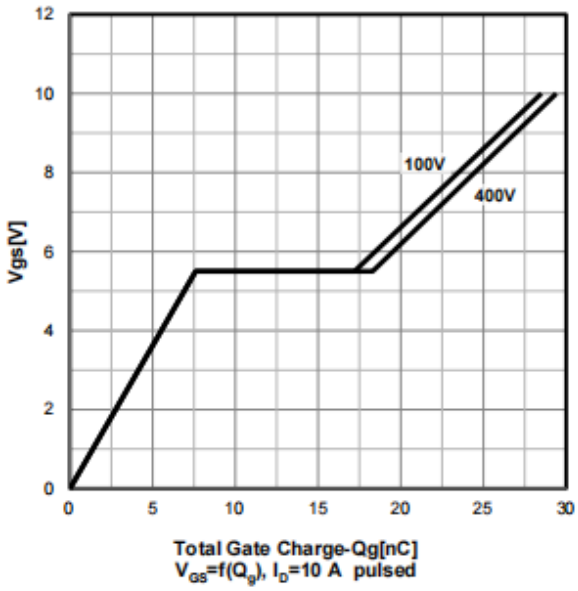
On-resistance vs temperature



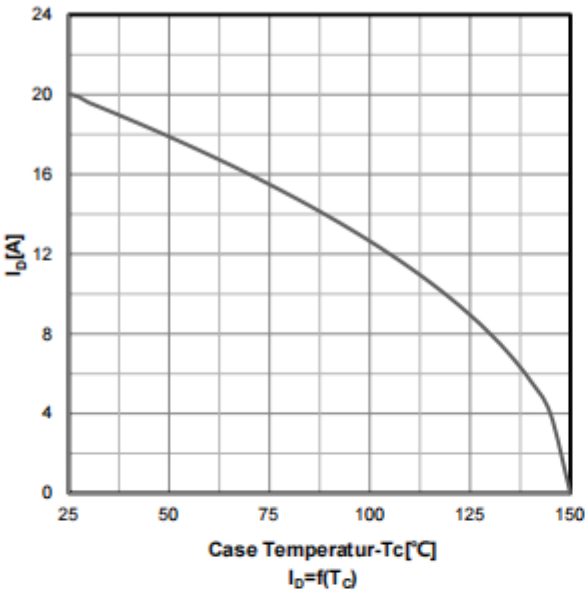
Typ. capacitances



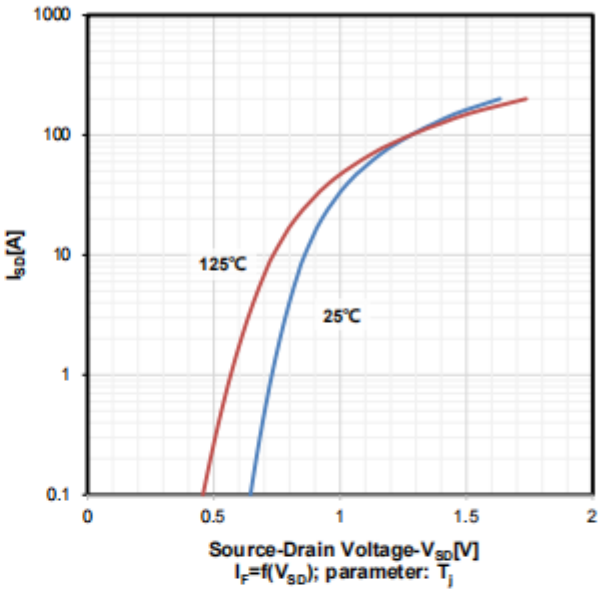
Typ. gate charge characteristics



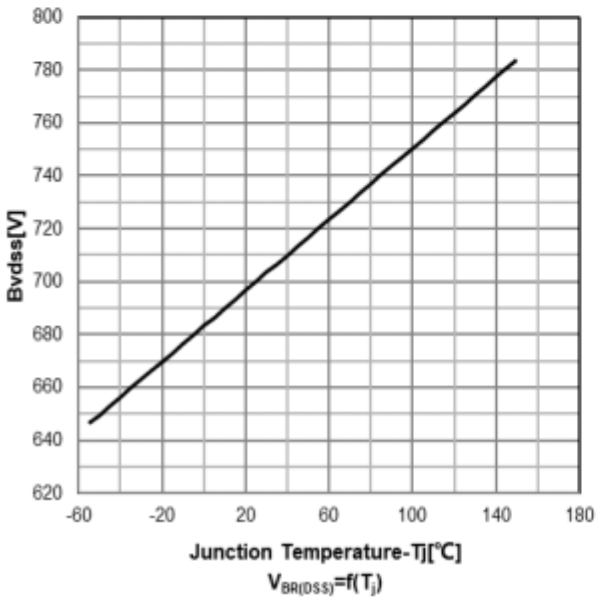
Drain current vs temperature



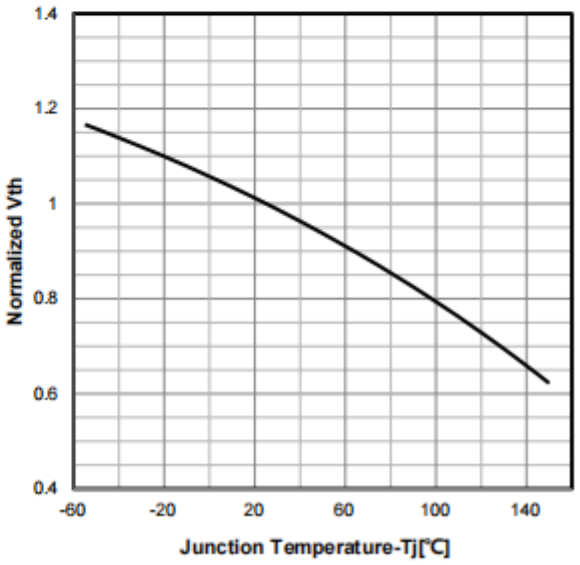
Forward characteristics of reverse diode



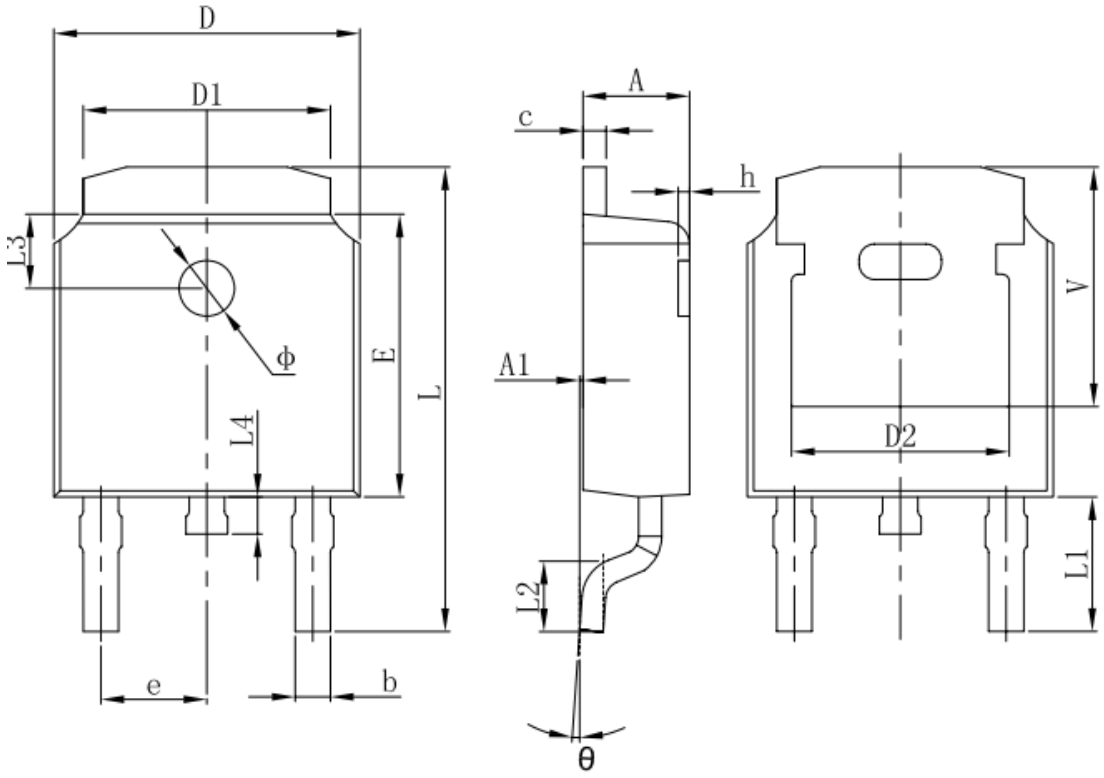
Drain-source breakdown voltage



Normalized $V_{GS(th)}$ characteristics



TO252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.635	0.770	0.025	0.030
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.712	10.312	0.382	0.406
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.250 REF.		0.207 REF.	

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